Serial No. 10/050,384

In the Claims:

Please amend the claims as follows:

1. (Currently Amended) A method of manufacturing a structural frame for dissipating heat from an electronic device, comprising:

providing a base polymer matrix;

mixing a thermally conductive filler material into said base polymer matrix to form molding material having a uniform distribution of said conductive filler material throughout said entire molding material;

net-shape injection molding said molding material into a highly thermally conductive structural frame for supporting electronic components, wherein said thermal conductivity of said structural frame creates a thermally conductive pathway through the structural frame from an interior portion of said frame to an exterior portion of said frame;

providing an electronic circuit board, said electronic circuit board having a heat generating electronic component disposed thereon; and

mounting said electronic circuit board in direct physical contact with the interior portion of said structural frame with said electronic component being in thermal communication with said structural frame via said electronic circuit board;

conducting heat from said heat generating electronic component along said thermally conductive pathway from said interior portion of said structural frame to said exterior portion of said structural frame; and

dissipating said conducted heat to the atmosphere from said exterior portion of said structural frame.

2. (Original) The method of manufacturing a structural frame of Claim 1, wherein said base polymer matrix is liquid crystal polymer.

3. (Original) The method of manufacturing a structural frame of Claim 1, wherein said thermally conductive filler material is selected from the group consisting of carbon fiber, metallic flakes, boron nitride and mixtures thereof.